

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1. (Original) An integrated circuit chip comprising:
a substrate, the substrates comprising a plurality of chip structures;
a plurality of bonding pads disposed on the substrate, each of the bonding pads being formed from an aluminum bearing material;
a surface region formed on each of the bonding pads;
an under bump metal layer overlying the surface region;
a wetting layer formed overlying the surface region, the wetting layer comprising a plurality of protrusions extending out of the wetting layer and disposed spatially on the wetting layer;
a bump layer overlying the wetting layer and mechanically coupling the plurality of protrusions.
2. (Original) The chip of claim 1 wherein the under bump metal comprises an adhesive material, a wetting material, and a protective material.
3. (Currently Amended) The chip of claim 1 wherein each of the protrusions has a predetermined height and a predetermined predetermined width.
4. (Original) The chip of claim 1 wherein each of the protrusions has a predetermined height, the height ranging from about 15 to about 20 microns.
5. (Original) The chip of claim 1 wherein each of the bonding pads has a dimension of about 80 microns by about 80 microns.
6. (Original) The chip of claim 1 wherein the wetting layer is provided by a deposition or plating process.

7. (Original) The chip of claim 1 wherein the plurality of protrusions prevents a possibility of the bump layer from peeling from the surface region of the bonding pad.

8. (Original) The chip of claim 1 wherein the plurality of protrusions prevents a possibility of the bump layer from peeling from the surface region during a reflow process.

9. (Original) The chip of claim 1 wherein the substrate comprises silicon.

10. (Original) The chip of claim 1 wherein the substrate is a silicon on insulator wafer.

11. (Original) A method for fabricating an integrated circuit chip comprising:
providing a substrate;
forming a plurality of bonding pads overlying the substrate, each of the bonding pads being formed from an aluminum bearing material and including a surface region;
forming an under bump metal layer overlying the surface region;
forming a wetting layer overlying the under bump metal layer, the wetting layer comprising a plurality of protrusions extending out of the wetting layer and disposed spatially on the wetting layer; and
forming a bump layer overlying the wetting layer and mechanically coupling to the plurality of protrusions.

12. (Currently Amended) The method of claim 11 wherein the under bump metrology metal comprises an adhesive material, a wetting material, and a protective material.

13. (Currently Amended) The method of claim 11 wherein each of the protrusions has a predetermined height and a predetermined predetermined width.

14. (Original) The method of claim 11 wherein each of the protrusions has a predetermined height, the height ranging from about 15 to about 20 microns.

15. (Original) The method of claim 11 wherein each of the bonding pads has a dimension of about 80 microns by about 80 microns.

16. (Original) The method of claim 11 wherein the wetting layer is provided by a deposition or plating process.
17. (Original) The method of claim 11 wherein the plurality of protrusions prevents a possibility of the bump layer from peeling from the surface region of the bonding pad.
18. (Original) The method of claim 11 further comprising reflowing the bump layer while maintaining the bump layer on the surface region through the plurality of protrusions.